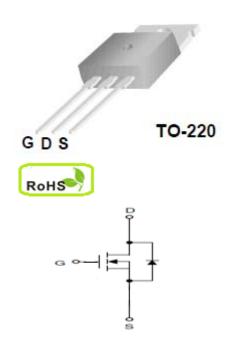
SKD470T 40V N-Channel MOSFET

■ FEATURES

- 40V/200A³
 RDS(ON)= 2.6mΩ typ@ VGS=10V
- Lead free and Green Device Available
- Low Rds-on to Minimize Conductive Loss
- High avalanche Current
- Application
- Power Supply
- Power Tool
- Load Switch Control

■ PIN DESCRIPTION



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter		Maximum	Unit	
V_{DSS}	Drain-to-Source Voltage		40	V	
V_{GSS}	Gate-to-Source Voltage		±20	V	
I _D ³	Continuous Drain Current	T _C =25°C	200	А	
		T _C =100°C	135		
l _{DP} ⁴	Pulsed Drain Current	T _C =25°C	750		
IAS⁵	Avalanche Current		30		
EAS⁵	Avalanche energy		1.1	J	
PD	Maximum Power Dissipation	T _C =25°C T _C =100°C	215	W	
		T _C =100°C	105		
$T_{J_1} T_{STG}$	Junction & Storage Temperature Range		-55~175	°C	

Thermal Characteristics

Symbol	Parameter	Typical	Unit
Rθjc	Thermal Resistance-Junction to Case	0.65	°C/W
Rθja	Thermal Resistance-Junction to Ambient	62.5	C/VV

SKD470T 40V N-Channel MOSFET

El	ectrical	Characteristics	(TA=25°C unless otherwise noted)
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Symbol	Parameter	Test Conditions	Min.	Тур	Max.	Unit
Static Cha	racteristics					•
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D =250uA	40	_	_	V
	Zero Gate Voltage Drain Current	V _{DS} =32V,V _{GS} =0V	_	_	1	uA
I _{DSS}		T _J =125°C	_	_	10	
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250uA	2	3	4	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	_	_	±100	nA
	Drain-Source On-Resistance	V _{GS} =10V, I _D =60A		2.5	4	mΩ
R _{DS(on)} ¹			_	_	_	
Diode Cha	aracteristics					
V _{SD} ¹	Diode Forward Voltage	I _{SD} =60A,V _{GS} =0V	_	_	1.3	V
ls ³	Diode Continuous Forward Current		_	_	250	Α
t _{rr}	Reverse Recovery Time	I _F =60A,	_	36	_	nS
Q _{rr}	Reverse Recovery Charge	dl/dt=100A/us	_	60	_	nC
Dynamic (Characteristics ²					
R_{G}	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Frequency=1MHz	_	1.1	_	Ω
C _{iss}	Input Capacitance		_	5700	_	pF
C _{oss}	Output Capacitance	V_{GS} =0V, V_{DS} =25V		1450	_	
C _{rss}	Reverse Transfer Capacitance	Frequency=1MHz		590		
t _{d(on)}	Turn-On Delay Time			35		
t _r	Turn-On Rise Time	V_{DD} =30V, I_{D} =60A, V_{GS} =10V, R_{G} =6 Ω	_	20	_	nS
$t_{d(off)}$	Turn-Off Delay Time			45	_	
t _f	Turn-Off Fall Time			62		
Gate Charg	ge Characteristics ²			•		
Q_{q}	Total Gate Charge	\/ -22\/\/ -40\/	_	155	_	nC
Q_{gs}	Gate-to-Source Charge	V_{DS} =32V, V_{GS} =10V	_	30	_	
Q_{gd}	Gate-to-Drain Charge	I _D =60A	_	66	_	

Note: 1: Pulse test; pulse width ≤ 300 us, duty cycle $\leq 2\%$.

^{2:} Guaranteed by design, not subject to production testing.

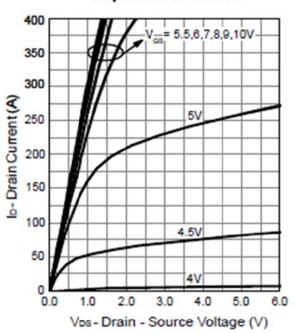
^{3:} Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 55A.

^{4:} Repetitive rating, pulse width limited by max junction temperature.

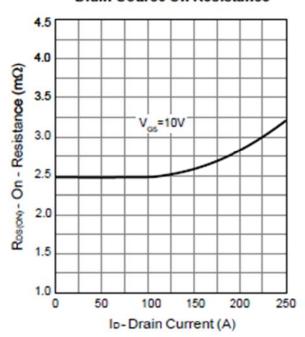
^{5:} Starting $TJ = 25^{\circ}C, L = 1mH$

Typical Operating Characteristics

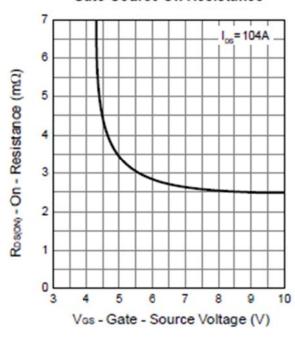
Output Characteristics



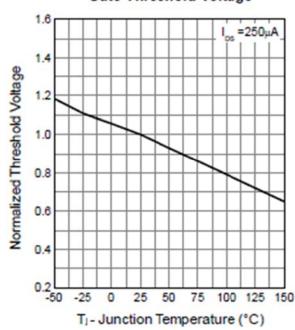
Drain-Source On Resistance



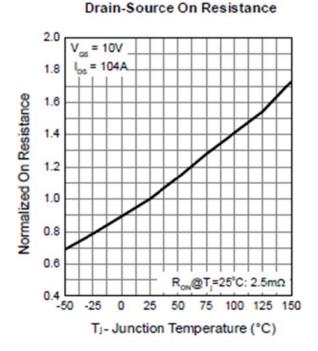
Gate-Source On Resistance



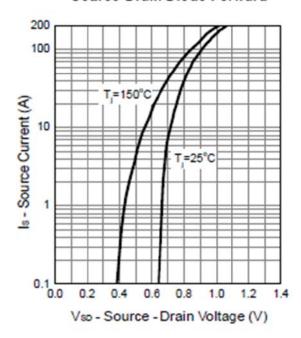
Gate Threshold Voltage



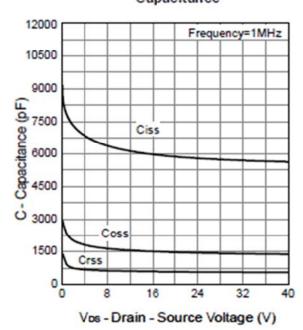
Typical Operating Characteristics



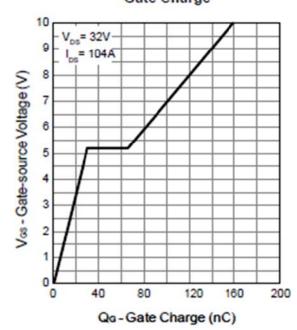
Source-Drain Diode Forward



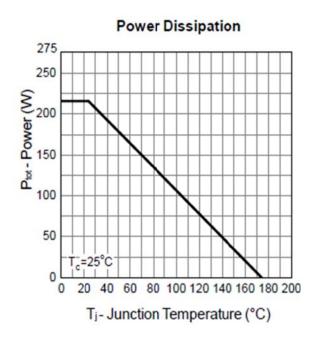
Capacitance

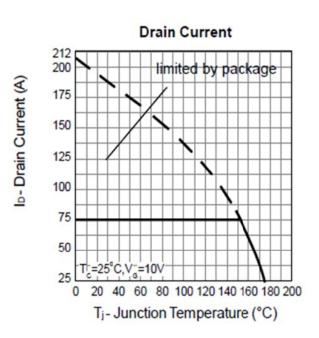


Gate Charge



Typical Operating Characteristics





Thermal Transient Impedance

